

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

Original claims 1-17 and Amended claims 1-11 (cancelled).

Claim 18 (new): A device for encapsulating with encapsulating material an electronic component, in particular a semiconductor, fixed on a carrier, comprising:

two co-acting mould parts which are displaceable relative to each other between an encapsulating position, in which the mould parts, when closing onto the carrier, occupy a position for defining at least one mould cavity, and an opened position in which the mould parts are situated at a greater distance from each other than in the encapsulating position, and

feed means, for encapsulating material connecting onto at least one projecting edge under which is located a receiving space for a part of the carrier, wherein the projecting edge forms a stationary assembly with one of the mould parts, which mould part also receives a support for the carrier that is displaceable relative to the edge such that the carrier can be urged against the projecting edge with a controllable force.

Claim 19 (new): The device as claimed in claim 18, wherein the projecting edge is defined by a material strip.

Claim 20 (new): The device as claimed in claim 19, wherein the material strip is assembled releasably with a mould part.

Claim 21 (new): The device as claimed in claim 18, wherein the displaceable support forms a side of the receiving space for a part of the carrier.

Claim 22 (new): The device as claimed in claim 18, wherein the device is provided with release means for displacing the carrier in the direction of the displaceable support.

Claim 23 (new): The device as claimed in claim 18, wherein the release means are formed by at least one pressure element arranged in the second mould part for displacement under bias.

Claim 24 (new): The device as claimed in claim 23, wherein the pressure element is connected to a control member which, in the situation of mould parts being closed together, urges the pressure element into a position where the pressure element lies clear of the carrier.

Claim 25 (new): A method for encapsulating with encapsulating material an electronic component, in particular a semiconductor, fixed on a carrier, comprising the processing steps of:

- A) placing the carrier on a first mould part such that at least one projecting edge connected to the first mould part lies on the side opposite the side of the carrier supporting on the first mould part,
- B) reducing the distance between the projecting edge and a support part of the first mould part supporting the carrier such that a part of the carrier is clamped between the part of the first mould part supporting the carrier and the projecting edge,
- C) closing a second mould part onto the first mould part such that at least one mould cavity is formed closing onto the carrier, and
- D) feeding liquid encapsulating material to the mould cavity,

wherein during step B) the support part is moved in the first mould part towards the projecting edge that is kept stationary.

Claim 26 (new): The method as claimed in claim 25, wherein the carrier is rotated relative to the projecting edge.

Claim 27 (new): The method as claimed in claim 25, wherein the first and second mould parts are moved apart and the carrier with the encapsulation arranged thereon and the remaining part of the cured encapsulating material are then removed from the first mould part in the situation where they are separated from each other.

Claim 28 (new): The method as claimed in claim 25, wherein after closing a second mould part onto the first mould part as according to processing step C), the mould parts are moved apart a distance of 1 to 50 μm , whereafter the distance between the projecting edge and the support part of the first mould part supporting the carrier is reduced such that a part of the carrier is clamped with a controllable force between the support part of the first mould part and the projecting edge.